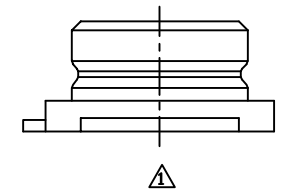


Cut Out Prohibition Area
Recommended P.C.B. Pattern



RoHS Compliant

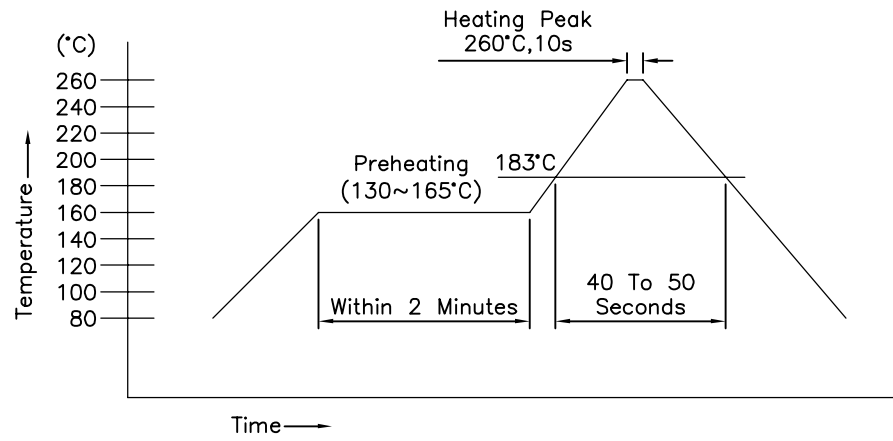
No.	Description	Material	Remark
1	Insulator	LCP	UL94V-0
2	Center Contact	Brass	Gold Flash Over Nickel
3	Ground Contact	Brass	Gold Flash Over Nickel

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4UCON TECHNOLOGY INC.

DRAWING No.		APPROVED BY		UNLESS OTHERWISE SPECIFIED TOLERANCES ARE .X ±0.38 .XX ±0.25 ANG.
18588		EMILY		
		CHECKED BY HZF		
		DRAWING BY SONG		
SCALE	NONE	REV.	A1	UNIT mm

NO.	REV.	REVISIONS	CHK	DATE
△	A1	Modify Data	HZF	07/10/2012
△	A0	NEW RELEASE	HZF	11/05/2007

Item	Specification	Conditions
1.Contact Resistance	Center:20 Milliohms Max. Outside:10 Milliohms Max.	Measured At 10mA Max.
2.Insulation Resistance	500 Megaohms Min.	Measured At 100V DC
3.Withstand Voltage	No Line Or Insulation Breakdown	200V AC For 1 Minute
4.V.S.W.R.	1.3 Max.	0 To 6 GHz
5.Female Contact Holding Force	0.15N Min.	Measured With A ϕ 0.475 Pin Gauge
6.Repetitive Operation	Contact Resistance 25 Milliohms Max. (Center) 15 Milliohms Max. (Outside)	30 Cycles Of Insertion And Disengagement
7.Vibration	No Momentary Disconnections Of 1 μ S Min. No Damage,Cracks,Or Parts Looseness Min.	Frequency If 10 To 100 Hz,Single Amplitude Of 1.5mm,Acceleration Of 59 m/s ² For 5 Cycles In The Direction Of Each Of The 3 Axes.
8.Shock	No Momentary Disconnections Of 1 μ S Min. No Damage,Cracks,Or Parts Looseness Min.	Acceleration Of 735m/s ² ,11ms Duartion Sine Half-Wave Waveform For 6 Cycles In The Direction Of Each Of The 3 Axes.
9.Humidity Resistance Steady State	No Damage,Cracks,Or Parts Looseness Min. Insulation Resistance 100 Megaohms Min. (High Temperature) Insulation Resistance 500 Megaohms Min. (Pry)	Temperature Of 40°C,Humidity Of 95% Let Stand For 96 Hours
10.Temperature Cycle	No Damage,Cracks,Or Parts Looseness Min. Contact Resistance 25 Milliohms Max. (Center) 15 Milliohms Max. (Outside)	Temperature:-40°C->+5°C To 35°C->+90°C->+5°C To 35°C Time: 30 Min.->3 Min.->30 Min.->3 Min. Cycles:5



- Note:
- (1) The Temperature Indicates The Printed Circuit Board Surface Temperature Of The Connector Lead Portion.
 - (2) The Reflow Soldering Method Should Be Performed At A Peak Temperature Of 260°C Or Less At The Surface Of Printed Circuit Board.
 - (3) The Temperature Profile Will Change Depending On Conditions Which Include Such Factors As The Size Of The Board,The Solder Used,And The Solder Thickness.

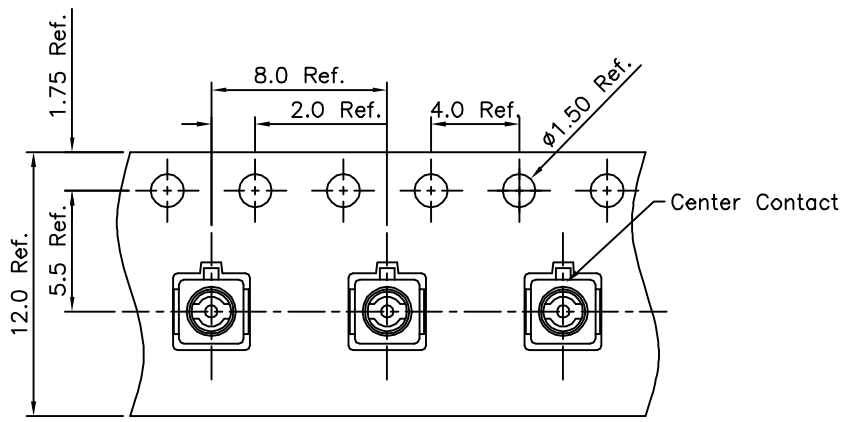
Recommended Timing And Temperature Of Hand Soldering(Reference)	Soldering Iron Temperature:350°C Soldering Time:3~5 Seconds
Recommended Screen Thickness	0.15mm

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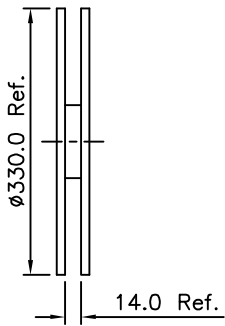
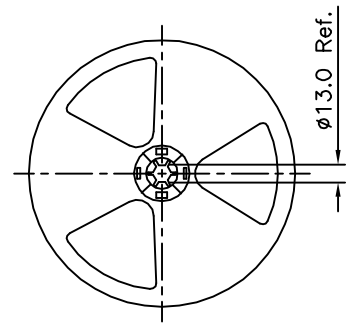
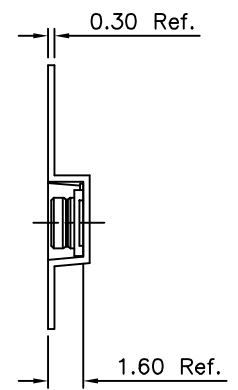
DRAWING No.		APPROVED BY		UNLESS OTHERWISE SPECIFIED TOLERANCES ARE .X \pm 0.38 .XX \pm 0.25 ANG.
18588		EMILY		
		CHECKED BY HZF		
		DRAWING BY SONG		
SCALE	NONE	REV.	A1	UNIT mm

NO.	REV.	REVISIONS	CHK	DATE
	A1	Modify Data	HZF	07/10/2012
	A0	NEW RELEASE	HZF	11/05/2007

SPECIFICATION
 Q'ty:2500 PCS/Reel
 RoHS Compliant



Dimensions Of Taping



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18588		EMILY		
		CHECKED BY		
		HZF		
		DRAWING BY		
		SONG		
SCALE	NONE	REV.	A1	UNIT
				mm

NO.	REV.	REVISIONS	CHK	DATE
△ A1		Modify Data	HZF	07/10/2012
△ A0		NEW RELEASE	HZF	11/05/2007